


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	ADG/22/13511	
<b>1.3 Title of PCI</b>	Die thickness change for ECMF4-2450A60N10	
<b>1.4 Product Category</b>	ECMF4-2450A60N10	
<b>1.5 Issue date</b>	2022-07-01	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Stephane CHAMARD
<b>2.1.2 Marketing Manager</b>	Philippe LEGER
<b>2.1.3 Quality Manager</b>	Jean-Paul REBRASSE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Wafer Fab (Process)	Backside finish modification except for wafer for sale: change final wafer thickness	STMicroelectronics Tours - France

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Thinnest die (part of ECMF4-2450A60N10) is of 90µm thickness.	Increase the thickness of the thinnest die (part of ECMF4-2450A60N10) from 90µm to 125µm.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	In the frame of production yields optimization, STMicroelectronics has decided to increase the thickness of the thinnest die (part of ECMF4-2450A60N10) from 90µm to 125µm. New die thickness is already qualified for other product ECMF4-40A100N10 (directly qualified with this new 125µm thickness).
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability of the change will be ensured by Finished Good/Type print on carton labels.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-06-20
<b>7.2 Intended start of delivery</b>	2022-10-07
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13511 18054QRP v2.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-07-01

**9. Attachments (additional documentations)**

13511 Public product.pdf  
13511 ECMF4-2450A60N10 die thickness.pdf  
13511 18054QRP v2.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ECMF4-2450A60N10	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCI Title** : Die thickness change for ECMF4-2450A60N10

**PCI Reference** : ADG/22/13511

**Subject** : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

ECMF4-2450A60N10		
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